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Dimensions

Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
T	0.8mm +/-0.07mm
S	0.7mm MIN
B	0.35mm +/-0.15mm

Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

General Information

Series	SMD Auto X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade
Features	High Temperature, Ultra-Stable, Automotive Grade
RoHS	Yes
Termination	Tin
Marking	No
Qualifications	AEC-Q200
AEC-Q200	Yes
Component Weight	4.8 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	3.3 pF
Measurement Condition	1 MHz 1.0Vrms
Capacitance Tolerance	+/-0.1 pF
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms